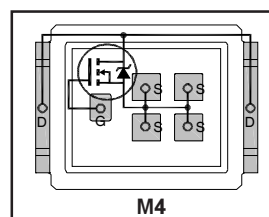


- Advanced Process Technology
- Optimized for Automotive DC-DC and other Heavy Load Applications
- Logic Level Gate Drive
- Exceptionally Small Footprint and Low Profile
- High Power Density
- Low Parasitic Parameters
- Dual Sided Cooling
- 175°C Operating Temperature
- Repetitive Avalanche Capability for Robustness and Reliability
- Lead Free, RoHS Compliant and Halogen Free
- Automotive Qualified *

$V_{(BR)DSS}$	100V
$R_{DS(on)}$ typ.	8.0mΩ
	max.
I_D (Silicon Limited)	51A
Q_g	44nC



Applicable DirectFET® Outline and Substrate Outline ①

SB	SC		M2	M4		L4	L6	L8	
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Description

The AUIRL7766M2 combines the latest Automotive HEXFET® Power MOSFET Silicon technology with the advanced DirectFET® packaging technology to achieve exceptional performance in a package that has the footprint of an SO-8 or 5X6mm PQFN and only 0.7mm profile. The DirectFET® package is compatible with existing layout geometries used in power applications, PCB assembly equipment and vapor phase, infrared or convection soldering techniques, when application note AN-1035 is followed regarding the manufacturing methods and processes. The DirectFET® package allows dual sided cooling to maximize thermal transfer in automotive power systems.

This HEXFET® Power MOSFET is designed for applications where efficiency and power density are of value. The advanced DirectFET® packaging platform coupled with the latest silicon technology allows the AUIRL7766M2 to offer substantial system level savings and performance improvement specifically in high frequency DC-DC and other heavy load applications on ICE, HEV and EV platforms. This MOSFET utilizes the latest processing techniques to achieve low on-resistance and low Qg per silicon area. Additional features of this MOSFET are 175°C operating junction temperature and high repetitive peak current capability. These features combine to make this MOSFET a highly efficient, robust and reliable device for high current automotive applications.

Absolute Maximum Ratings

Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
V_{DS}	Drain-to-Source Voltage	100	V
V_{GS}	Gate-to-Source Voltage	± 16	
$I_D @ T_C = 25°C$	Continuous Drain Current, $V_{GS} @ 10V$ (Silicon Limited)④	51	A
$I_D @ T_C = 100°C$	Continuous Drain Current, $V_{GS} @ 10V$ (Silicon Limited)④	36	
$I_D @ T_A = 25°C$	Continuous Drain Current, $V_{GS} @ 10V$ (Silicon Limited)③	10	
I_{DM}	Pulsed Drain Current ⑤	204	
$P_D @ T_C = 25°C$	Power Dissipation ④	62.5	W
$P_D @ T_A = 25°C$	Power Dissipation ③	2.5	
E_{AS}	Single Pulse Avalanche Energy (Thermally Limited) ⑥	61	mJ
$E_{AS} (tested)$	Single Pulse Avalanche Energy Tested Value ⑥	237	
I_{AR}	Avalanche Current ⑦	See Fig. 18a,18b,16,17	A
E_{AR}	Repetitive Avalanche Energy ⑦		mJ
T_P	Peak Soldering Temperature	270	°C
T_J	Operating Junction and	-55 to + 175	
T_{STG}	Storage Temperature Range		

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{θJA}$	Junction-to-Ambient ③	—	60	°C/W
$R_{θJA}$	Junction-to-Ambient ③	12.5	—	
$R_{θJA}$	Junction-to-Ambient ③	20	—	
$R_{θJCan}$	Junction-to-Can ④⑩	—	2.4	
$R_{θJ-PCB}$	Junction-to-PCB Mounted	1.0	—	
	Linear Derating Factor ④	0.42		W/°C

HEXFET® is a registered trademark of International Rectifier.

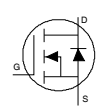
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

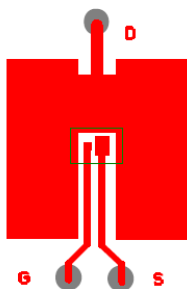
	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.067	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = 5.0\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	8.0	10	m Ω	$V_{GS} = 10V, I_D = 31A$ ⑦
		—	8.7	10.5		$V_{GS} = 4.5V, I_D = 26A$ ⑧
$V_{GS(th)}$	Gate Threshold Voltage	1.0	—	2.5	V	$V_{DS} = V_{GS}, I_D = 150\mu A$
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Coefficient	—	-7.3	—	mV/ $^\circ\text{C}$	
g_{fs}	Forward Transconductance	110	—	—	S	$V_{DS} = 25V, I_D = 31A$
R_G	Gate Resistance	—	0.88	—	Ω	
I_{DSS}	Drain-to-Source Leakage Current	—	—	5.0	μA	$V_{DS} = 100V, V_{GS} = 0V$
		—	—	250		$V_{DS} = 100V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 16V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -16V$

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

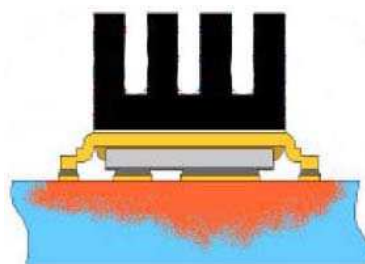
	Parameter	Min.	Typ.	Max.	Units	Conditions		
Q_g	Total Gate Charge	—	44	66	nC	$V_{DS} = 50V$ $V_{GS} = 4.5V$ $I_D = 31A$ See Fig.11		
Q_{gs1}	Pre-Vth Gate-to-Source Charge	—	9.6	—				
Q_{gs2}	Post-Vth Gate-to-Source Charge	—	4.5	—				
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	19	—				
Q_{godr}	Gate Charge Overdrive	—	10.9	—				
Q_{sw}	Switch Charge ($Q_{gs2} + Q_{gd}$)	—	23.5	—	nC	$V_{DS} = 16V, V_{GS} = 0V$		
Q_{oss}	Output Charge	—	35	—				
$t_{d(on)}$	Turn-On Delay Time	—	16	—			ns	$V_{DD} = 50V, V_{GS} = 10V$ ⑦ $I_D = 31A$ $R_G = 6.8\Omega$
t_r	Rise Time	—	24	—				
$t_{d(off)}$	Turn-Off Delay Time	—	120	—				
t_f	Fall Time	—	49	—				
C_{iss}	Input Capacitance	—	5305	—	pF	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1.0\text{MHz}$		
C_{oss}	Output Capacitance	—	460	—				
C_{riss}	Reverse Transfer Capacitance	—	195	—				
C_{oss}	Output Capacitance	—	2735	—				
C_{oss}	Output Capacitance	—	270	—				
$C_{oss\ eff.}$	Effective Output Capacitance	—	370	—				

Diode Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

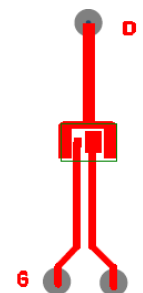
	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	51	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ⑨	—	—	204		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$I_S = 31A, V_{GS} = 0V$ ⑦
t_{rr}	Reverse Recovery Time	—	45	68	ns	$I_F = 31A, V_{DD} = 25V$
Q_{rr}	Reverse Recovery Charge	—	83	125	nC	$di/dt = 100A/\mu s$ ⑦



③ Surface mounted on 1 in. square Cu (still air).



⑨ Mounted to a PCB with small clip heatsink (still air)



⑩ Mounted on minimum footprint full size board with metalized back and with small clip heatsink (still air)

Notes ① through ⑩ are on page 11

Qualification Information[†]

Qualification Level		Automotive (per AEC-Q101) ^{††}	
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level		MEDIUM-CAN	MSL1, 260°C
ESD	Machine Model	Class M4 (+/- 800V) ^{†††} AEC-Q101-002	
	Human Body Model	Class H2 (+/- 3000V) ^{†††} AEC-Q101-001	
	Charged Device Model	N/A AEC-Q101-005	
RoHS Compliant		Yes	

† Qualification standards can be found at International Rectifier's web site: <http://www.irf.com>

†† Exceptions to AEC-Q101 requirements are noted in the qualification report.

††† Highest passing voltage.

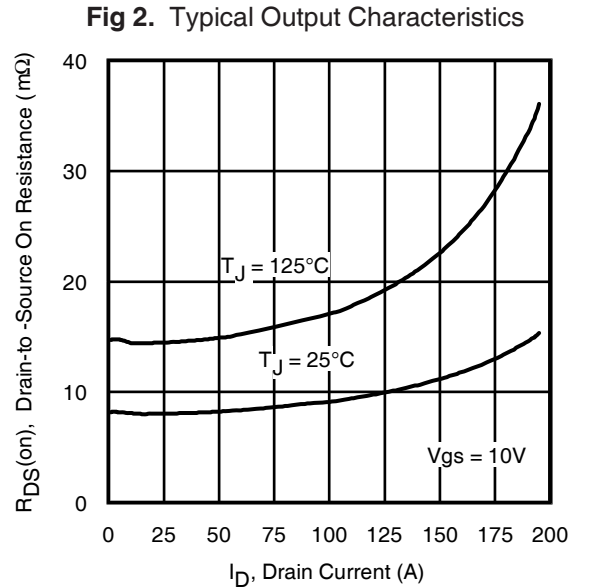
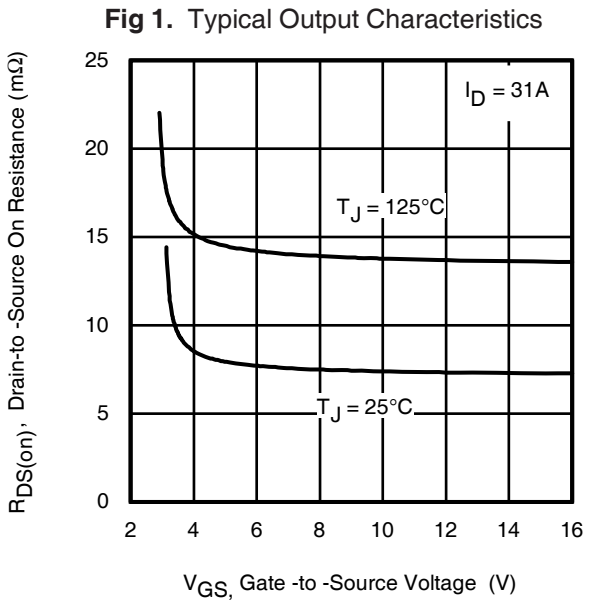
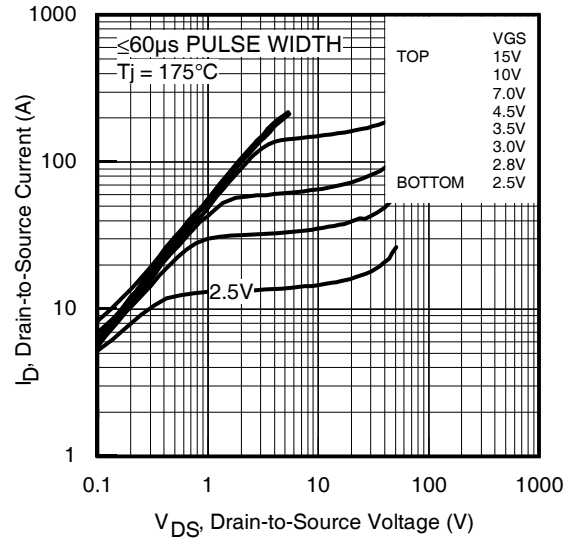
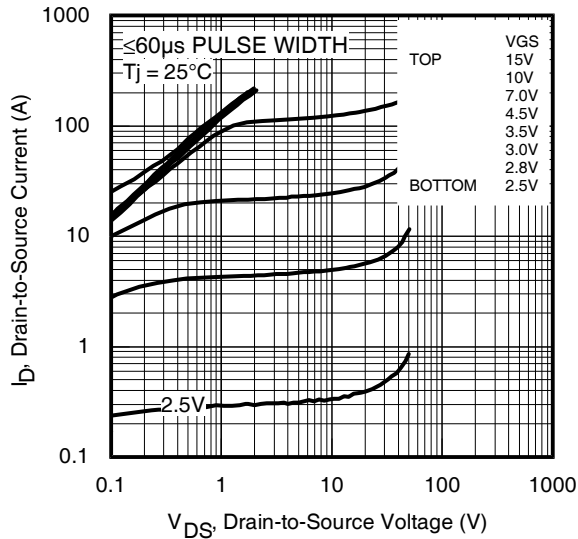


Fig 3. Typical On-Resistance vs. Gate Voltage

Fig 4. Typical On-Resistance vs. Drain Current

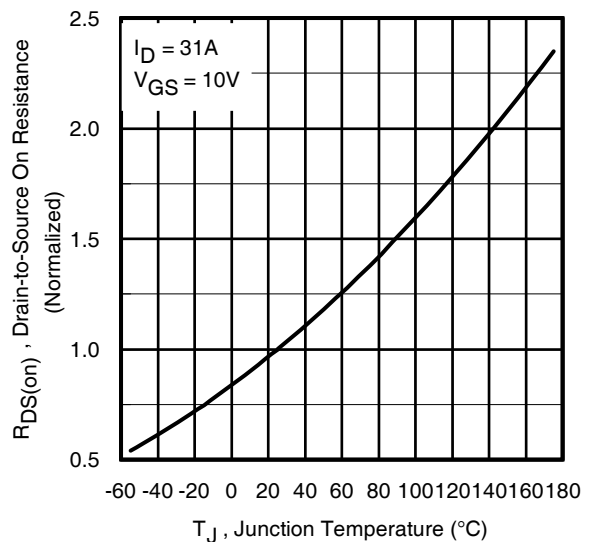
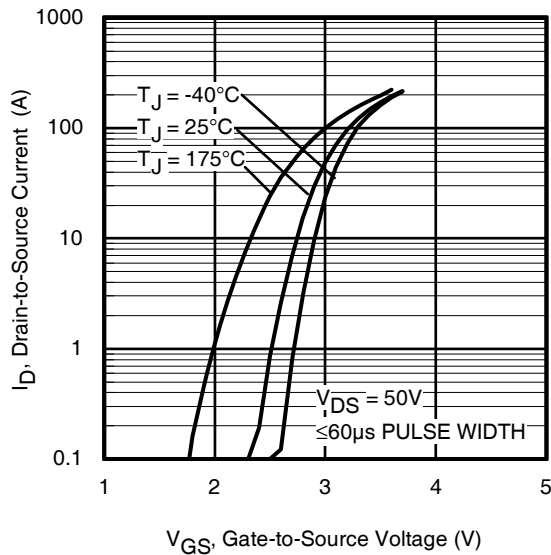


Fig 5. Typical Transfer Characteristics

Fig 6. Normalized On-Resistance vs. Temperature

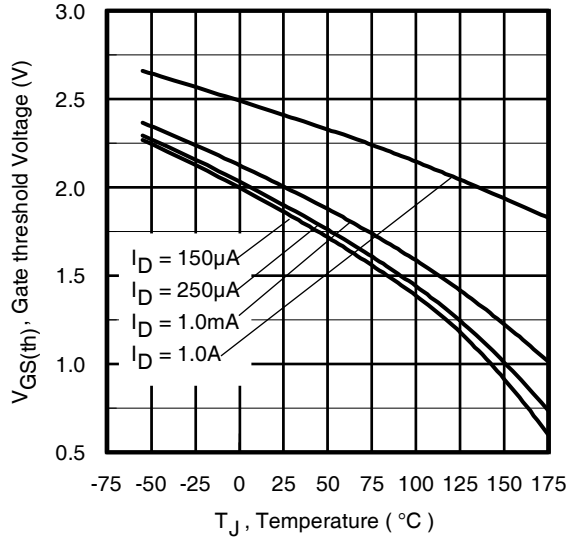


Fig 7. Typical Threshold Voltage vs. Junction Temperature

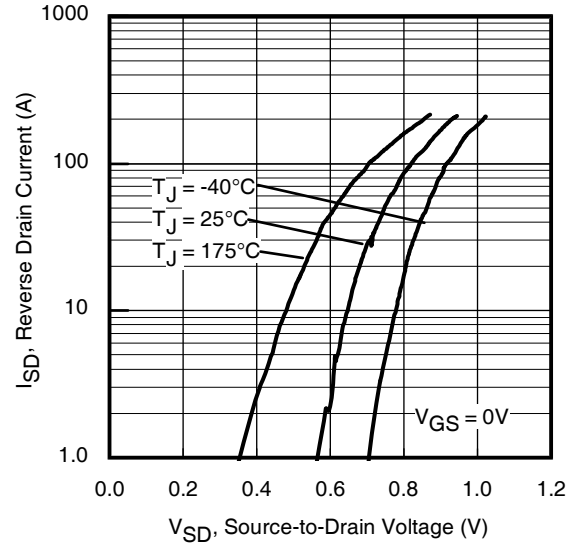


Fig 8. Typical Source-Drain Diode Forward Voltage

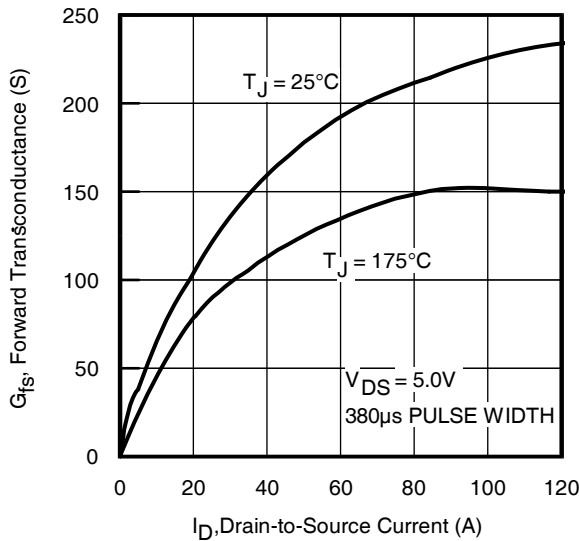


Fig 9. Typical Forward Transconductance vs. Drain Current

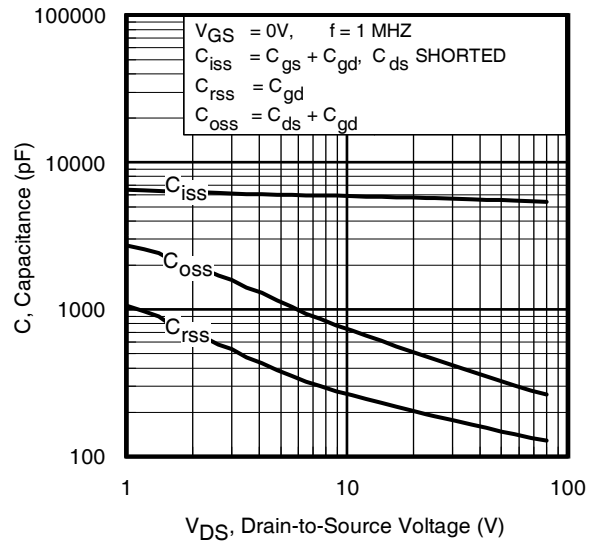


Fig 10. Typical Capacitance vs. Drain-to-Source Voltage

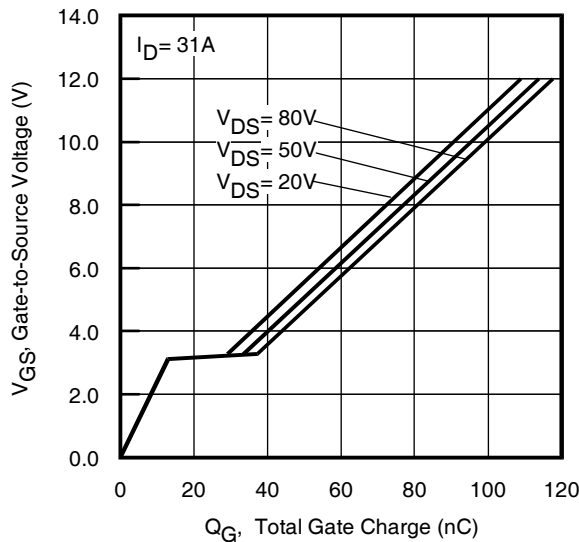


Fig 11 Typical Gate Charge vs. Gate-to-Source Voltage

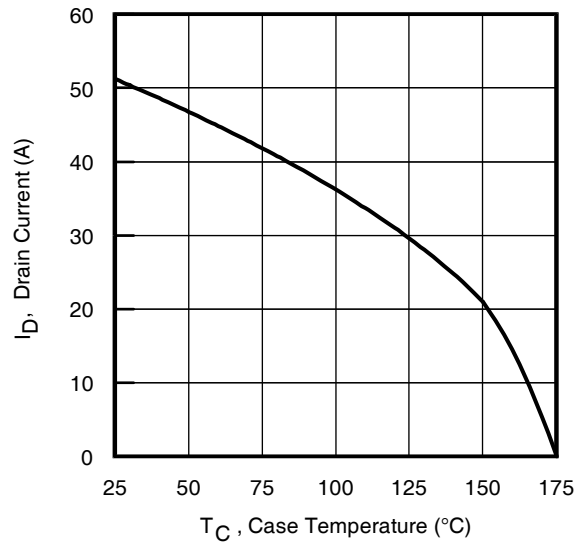


Fig 12. Maximum Drain Current vs. Case Temperature

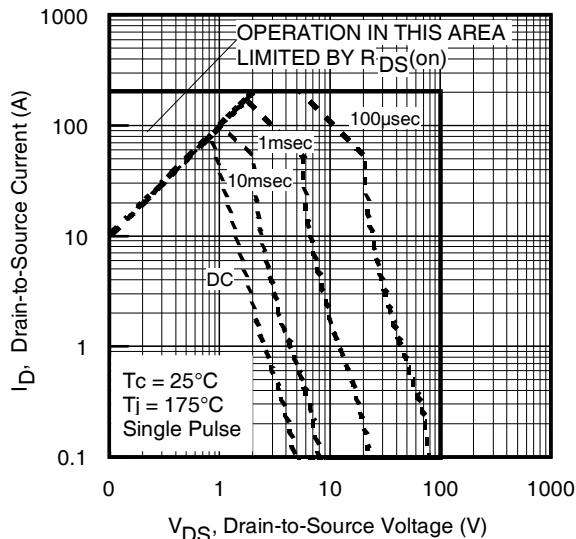


Fig 13. Maximum Safe Operating Area

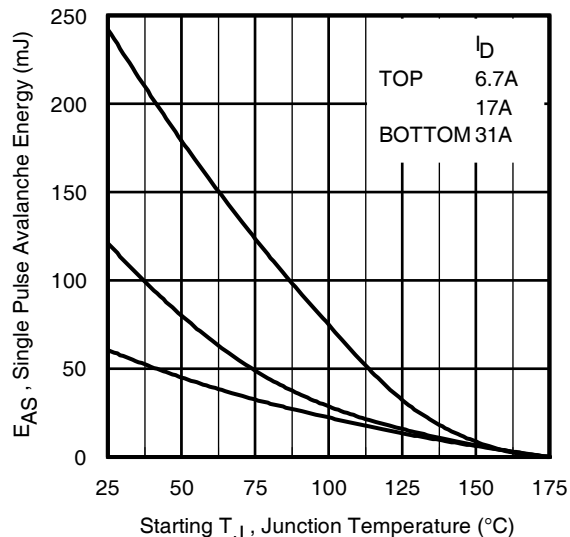


Fig 14. Maximum Avalanche Energy vs. Temperature

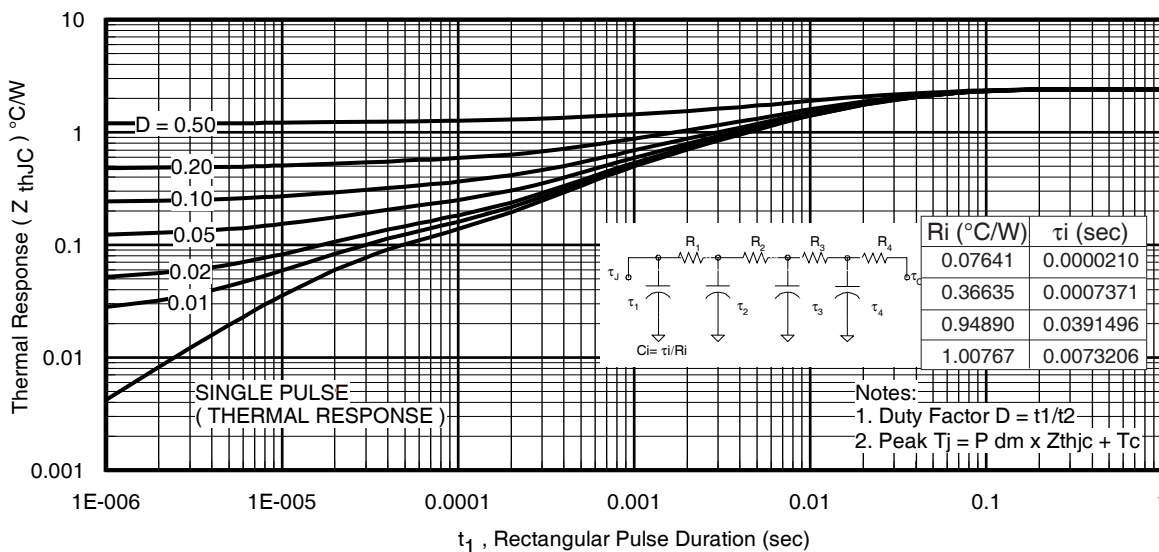


Fig 15. Maximum Effective Transient Thermal Impedance, Junction-to-Case

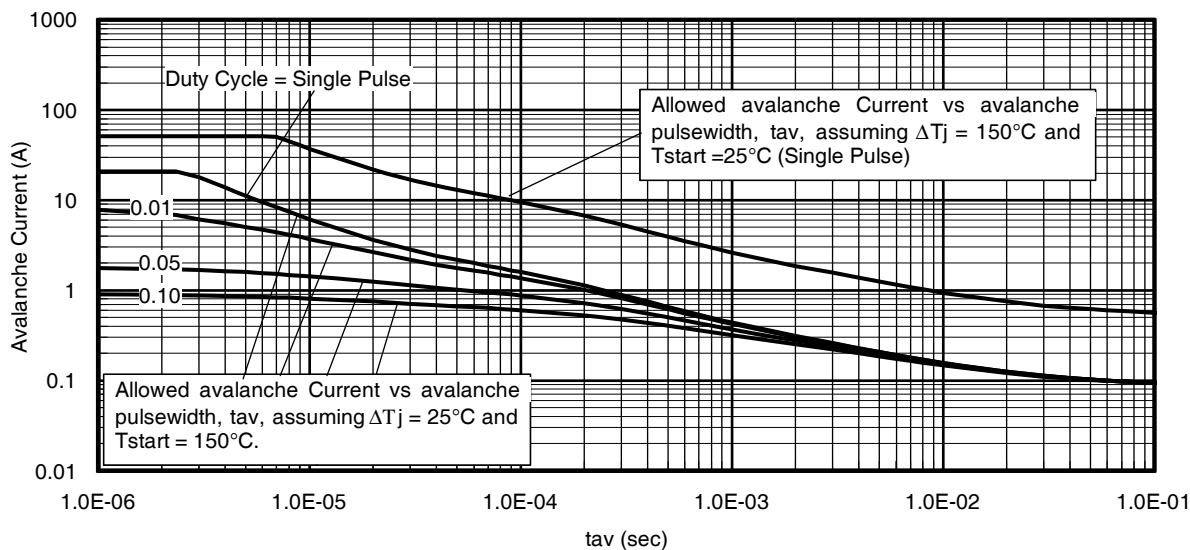


Fig 16. Typical Avalanche Current vs. Pulsewidth

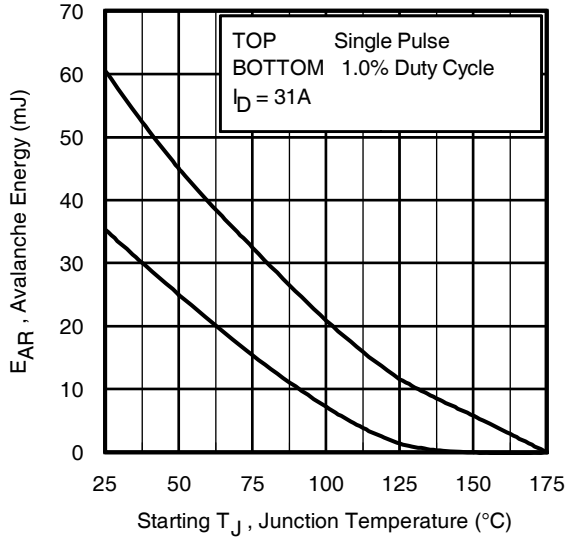


Fig 17. Maximum Avalanche Energy vs. Temperature

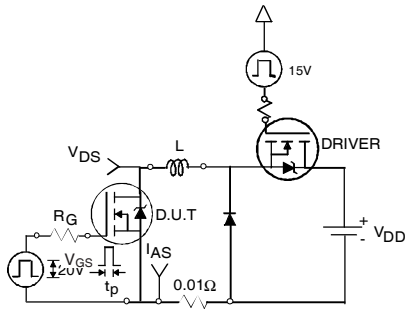


Fig 18a. Unclamped Inductive Test Circuit

$$P_{D(ave)} = 1/2 (1.3 \cdot BV \cdot I_{av}) \cdot \Delta T / Z_{thJC}$$

$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$

$$E_{AS(AR)} = P_{D(ave)} \cdot t_{av}$$

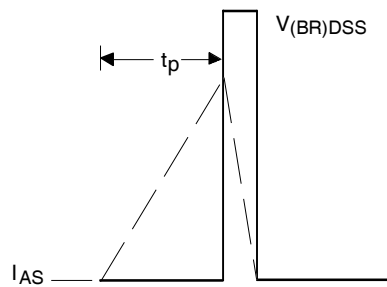


Fig 18b. Unclamped Inductive Waveforms

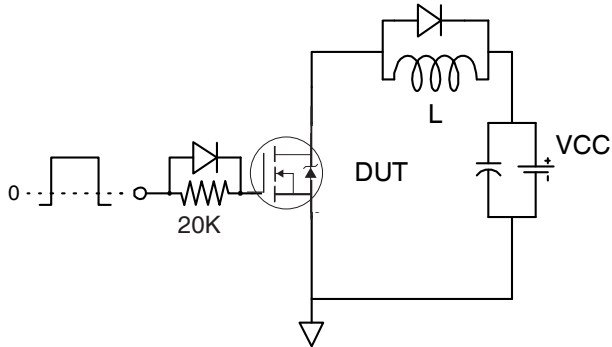


Fig 19a. Gate Charge Test Circuit

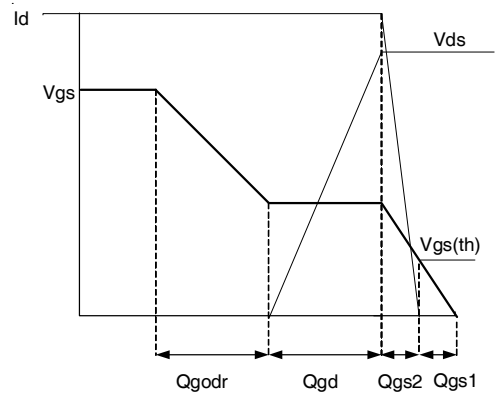


Fig 19b. Gate Charge Waveform

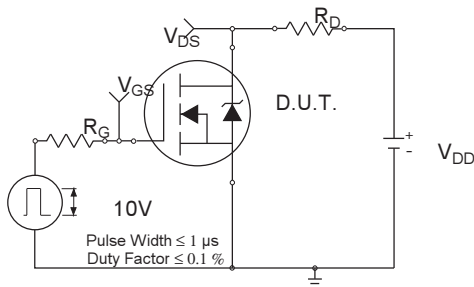


Fig 20a. Switching Time Test Circuit

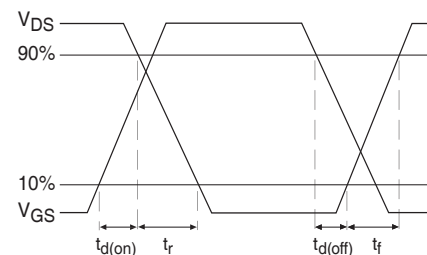
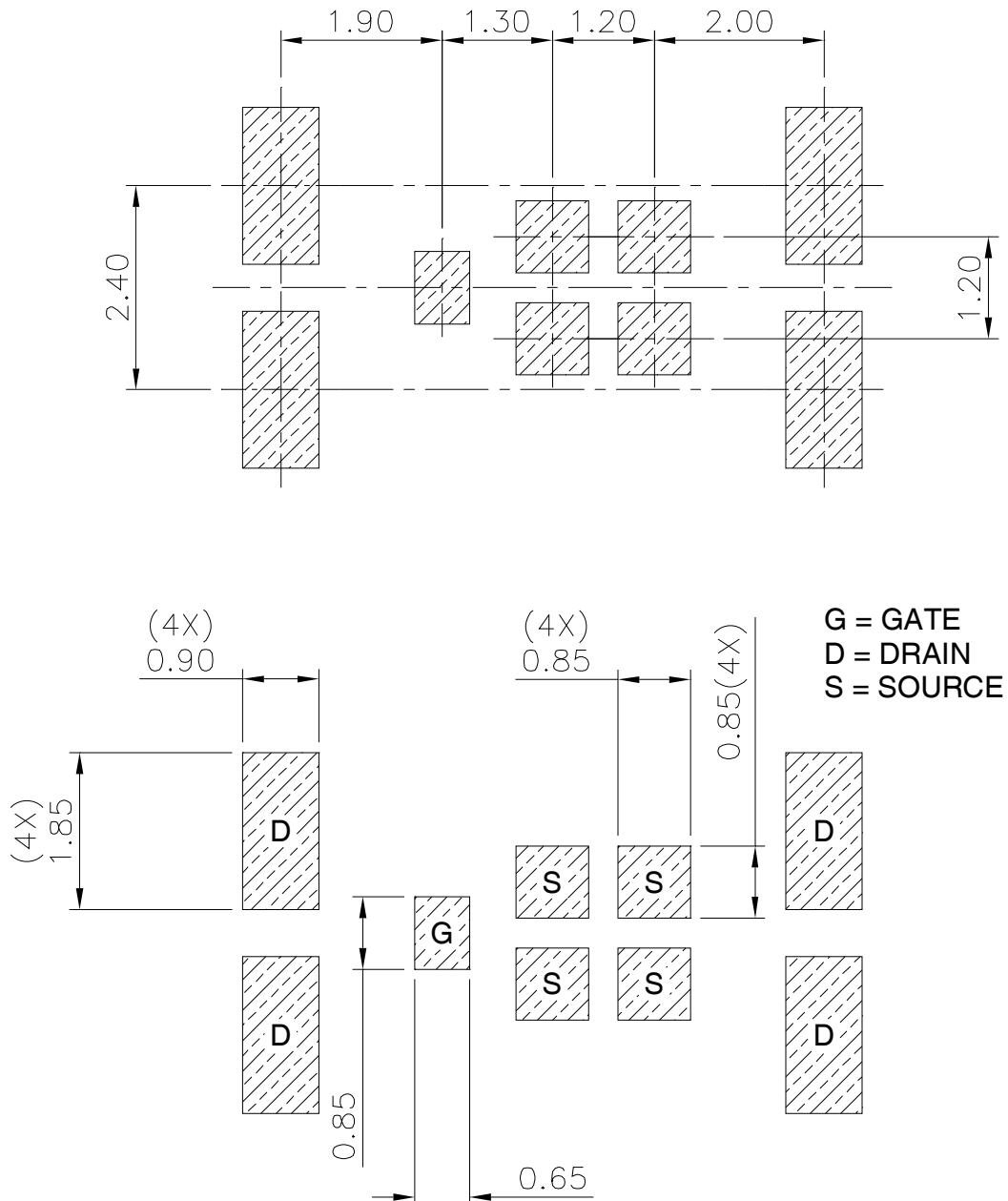


Fig 20b. Switching Time Waveforms

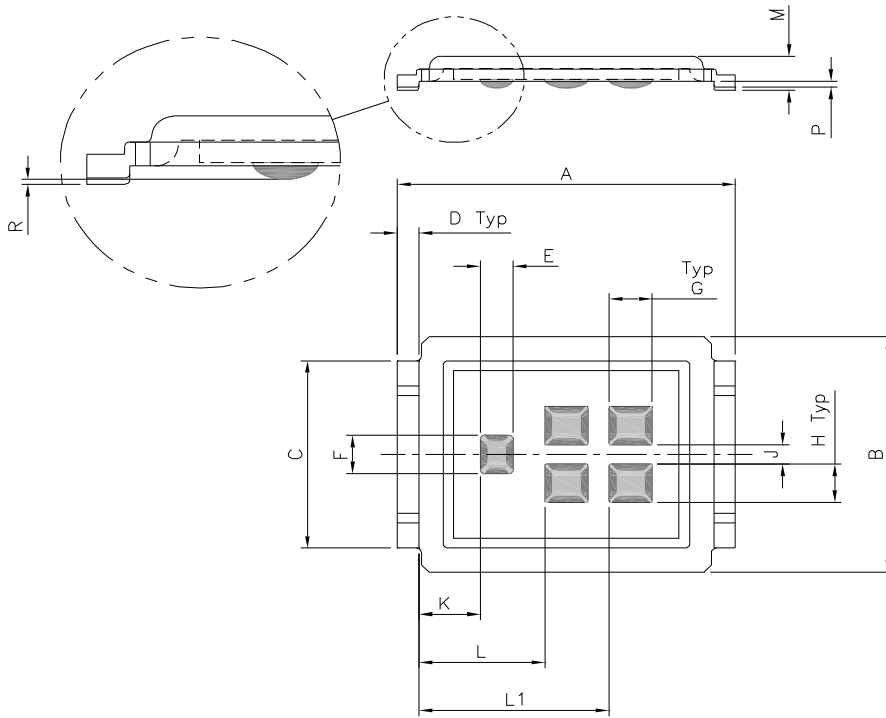
DirectFET® Board Footprint, M4 (Medium Size Can).

Please see AN-1035 for DirectFET® assembly details and stencil and substrate design recommendations



DirectFET® Outline Dimension, M4 Outline (Medium Size Can).

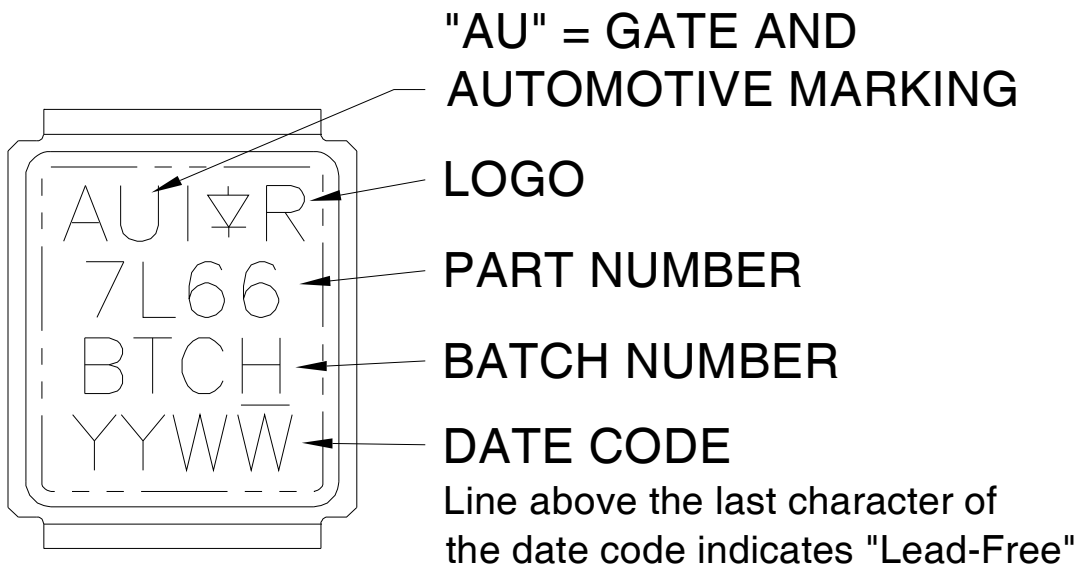
Please see AN-1035 for DirectFET® assembly details and stencil and substrate design recommendations



CODE	METRIC		IMPERIAL	
	MIN	MAX	MIN	MAX
A	6.25	6.35	0.246	0.250
B	4.80	5.05	0.189	0.199
C	3.85	3.95	0.152	0.156
D	0.35	0.45	0.014	0.018
E	0.58	0.62	0.023	0.024
F	0.78	0.82	0.031	0.032
G	0.78	0.82	0.031	0.032
H	0.78	0.82	0.031	0.032
J	0.38	0.42	0.015	0.017
K	1.10	1.20	0.043	0.047
L	2.30	2.40	0.090	0.094
L1	3.50	3.60	0.138	0.142
M	0.68	0.74	0.027	0.029
P	0.09	0.17	0.003	0.007
R	0.02	0.08	0.001	0.003

Dimensions are shown in millimeters (inches)

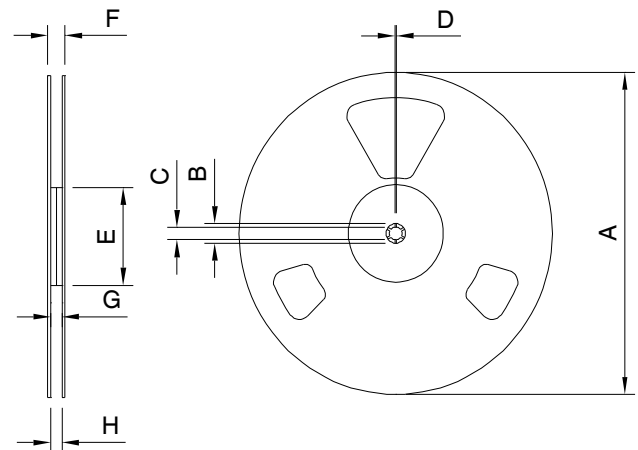
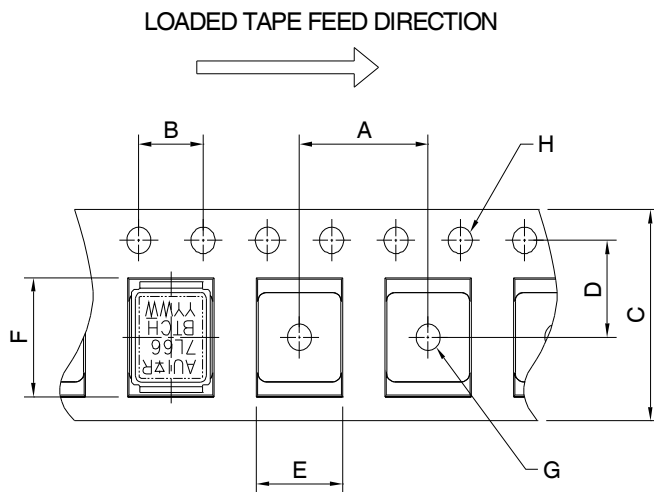
DirectFET® Part Marking



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

www.irf.com

DirectFET® Tape & Reel Dimension (Showing component orientation).



NOTE: Controlling dimensions in mm
Std reel quantity is 4800 parts. (ordered as AUIRL7766M2TR). For 1000 parts on 7" reel, order AUIRL7766M2TR1

NOTE: CONTROLLING DIMENSIONS IN MM

CODE	DIMENSIONS		DIMENSIONS	
	MIN	MAX	MIN	MAX
A	7.90	8.10	0.311	0.319
B	3.90	4.10	0.154	0.161
C	11.90	12.30	0.469	0.484
D	5.45	5.55	0.215	0.219
E	5.10	5.30	0.201	0.209
F	6.50	6.70	0.256	0.264
G	1.50	N.C	0.059	N.C
H	1.50	1.60	0.059	0.063

CODE	REEL DIMENSIONS							
	STANDARD OPTION (QTY 4800)				TR1 OPTION (QTY 1000)			
	METRIC		IMPERIAL		METRIC		IMPERIAL	
A	330.0	N.C	12.992	N.C	177.77	N.C	6.9	N.C
B	20.2	N.C	0.795	N.C	19.06	N.C	0.75	N.C
C	12.8	13.2	0.504	0.520	13.5	12.8	0.53	0.50
D	1.5	N.C	0.059	N.C	1.5	N.C	0.059	N.C
E	100.0	N.C	3.937	N.C	58.72	N.C	2.31	N.C
F	N.C	18.4	N.C	0.724	N.C	13.50	N.C	0.53
G	12.4	14.4	0.488	0.567	11.9	12.01	0.47	N.C
H	11.9	15.4	0.469	0.606	11.9	12.01	0.47	N.C

Notes:

- ① Click on this section to link to the appropriate technical paper.
- ② Click on this section to link to the DirectFET® Website.
- ③ Surface mounted on 1 in. square Cu board, steady state.
- ④ T_C measured with thermocouple mounted to top (Drain) of part.
- ⑤ Repetitive rating; pulse width limited by max. junction temperature.
- ⑥ Starting $T_J = 25^\circ\text{C}$, $L = 0.13\text{mH}$, $R_G = 50\Omega$, $I_{AS} = 31\text{A}$, $V_{GS} = 20\text{V}$.
- ⑦ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ⑧ Used double sided cooling, mounting pad with large heatsink.
- ⑨ Mounted on minimum footprint full size board with metalized back and with small clip heatsink.
- ⑩ R_θ is measured at T_J of approximately 90°C .

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IR products are neither designed nor intended for use in automotive applications or environments unless the specific IR products are designated by IR as compliant with ISO/TS 16949 requirements and bear a part number including the designation "AU". Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, IR will not be responsible for any failure to meet such requirements

For technical support, please contact IR's Technical Assistance Center
<http://www.irf.com/technical-info/>

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Tel: (310) 252-7105